



Material Content Data Sheet



Halogen-Free

Sales Product Name	BSC340N08NS3 G	Issued	17. February 2022
MA#	MA005699167		
Package	PG-TDSON-8-5	Weight*	123.61 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.830	0.67	0.67	6714	6714
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		92	
	non noble metal	iron	7439-89-6	0.038	0.03		306	
	non noble metal	copper	7440-50-8	37.762	30.55	30.59	305495	305893
wire	non noble metal	copper	7440-50-8	0.067	0.05	0.05	543	543
encapsulation	organic material	carbon black	1333-86-4	0.097	0.08		785	
	plastics	epoxy resin	-	6.887	5.57		55716	
	inorganic material	silicondioxide	60676-86-0	41.515	33.60	39.25	335862	392363
leadfinish	non noble metal	tin	7440-31-5	1.452	1.17	1.17	11744	11744
plating	noble metal	silver	7440-22-4	0.166	0.13	0.13	1339	1339
solder	non noble metal	tin	7440-31-5	0.023	0.02		183	
	noble metal	silver	7440-22-4	0.028	0.02		228	
	non noble metal	lead	7439-92-1	1.078	0.87	0.91	8717	9128
heat sink clip	inorganic material	phosphorus	7723-14-0	0.007	0.01		54	
	non noble metal	iron	7439-89-6	0.022	0.02		181	
	non noble metal	copper	7440-50-8	22.292	18.03	18.06	180341	180576
heatspreader	inorganic material	phosphorus	7723-14-0	0.003			28	
	non noble metal	iron	7439-89-6	0.011	0.01		92	
	non noble metal	copper	7440-50-8	11.320	9.16	9.17	91580	91700
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

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2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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